

In the Specification<sup>1</sup>

*Kindly replace the present specification with the substitute specification submitted herewith on separate pages.*

In the Claims<sup>2</sup>

*Kindly cancel Claims 2 and 26-28 without prejudice or disclaimer of their subject matter.*

*Kindly amend Claims 1 and 21 to read as follows:*

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1. (Amended) A plasma processing apparatus comprising:  
a chamber having a support for a substrate;  
at least one gas inlet into the chamber;  
means for alternately and repeatedly introducing an etch gas and a deposition gas into the chamber through the at least one gas inlet, wherein the deposition gas is different than the etch gas;  
means for striking a plasma into the etch gas and the deposition gas alternately introduced into the chamber;

<sup>1</sup> A copy of revised pages of the original specification showing additions and deletion thereto is attached as ATTACHMENT "B".

<sup>2</sup> A copy of any revised claims showing additions and deletions thereto is attached at ATTACHMENT "A".